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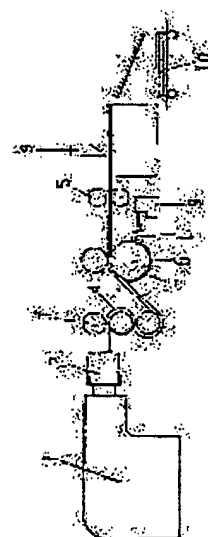
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(54) ELECTROMAGNETIC WAVE SHIELDING MATERIAL AND MANUFACTURE THEREOF

(57)Abstract:

PURPOSE: To obtain superior electromagnetic wave shielding material at lower cost by applying pressure to an electromagnetic wave shielding material consisting of conductive material and a little amount of adhesive material.

CONSTITUTION: A powdery electromagnetic wave shielding material consisting of a conductive material and adhesive are heat-pressed to a plastic material, which is extruded in a continuous production process using extrusion or T-die 2 for plastics products, with a roll 6 at a suitable temperature and pressure to provide conductivity to it and to closely unified to the rear side of many types of plates or on intermediate layer. For example, copper, nickel, tin, and aluminum as metal powder, many kinds of metal fiber, carbon fiber and metal coated organic fiber as a fiber conductor, and many kinds of polymer material and nonorganic adhesives are used as adhesives for conductive materials. Thus, the material is completely connected, with powder material showing complete electrical conductivity, providing favorable electromagnetic shielding characteristics.



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